

**R E M A R K S**

Reconsideration of this application, as amended, is respectfully requested.

**THE DRAWINGS**

It is respectfully pointed out that item 10(a) of item 10 of the Office Action Summary sheet was not completed, and it is respectfully requested that the Examiner check item 10(a) of the Office Action Summary sheet to confirm that the original drawings have been accepted.

**THE CLAIMS**

Claims 1-22 have been canceled, without prejudice, and new claims 23-33 have been added to more clearly recite the distinguishing features of the present invention based on disclosure throughout the specification and drawings. No new matter has been added, and it is respectfully requested that the amendments to the claims be approved and entered.

**THE PRIOR ART REJECTION**

Claims 1-10 and 15-17 were rejected under 35 USC 103 as being obvious in view of the combination of USP 5,456,608 ("Rogers et al") and USP 5,434,749 ("Nakayama"); and claims 11-14 were rejected under 35 USC 103 as being obvious in view of the combination of Rogers et al and Nakayama, and further in view of

one or more of USP 4,937,932 ("Ishii"), USP 5,836,582 ("Ogawa et al") and USP 5,718,057 ("Rosli et al"). These rejections, however, are respectfully traversed, to the extent that they are deemed to apply to new claims 23-33.

According to the present invention as recited in new independent claim 23, a circuit board is provided which comprises (i) a resin plate having anchor pins projecting from a surface thereof, wherein the resin plate includes a plurality of terminal receiving holes, and welding holes provided adjacent to the plurality of terminal receiving holes, and (ii) a circuit pattern that is punched out of a metal foil provided on the resin plate, wherein the metal foil has pin receiving holes into which the anchor pins of the resin plate are inserted. In addition, as recited in new claim 23, a plurality of metal tubular reception terminals are provided in the plurality of terminal receiving holes of the resin plate for receiving insertion terminals, and the tubular reception terminals include tab portions which are fixed on the circuit pattern by welding.

New independent claim 24, moreover, recites a method for manufacturing the circuit board of the present invention, and new independent claim 26 recites a joint box housing a plurality of the circuit boards of the present invention.

With the structure and method of the present invention as recited in new independent claims 23, 24 and 26, a circuit board

is integrally formed by providing a metal foil on a resin plate having projected anchor pins, and punching a circuit pattern out of the metal foil. In addition, with the structure and method of the present invention as recited in new independent claims 23, 24 and 26, the circuit pattern is fixed onto the resin plate by the anchor pins, reception terminals are inserted into terminal receiving holes formed in the resin plate, and tab portions which are provided on the reception terminals are fixed to the circuit pattern by welding.

By contrast, it is respectfully pointed out that Rogers et al, which was cited by the Examiner on page 4 of the Office Action with respect to the pin receiving holes and anchor pins of the present invention, merely discloses a circuit board 10 and separately formed connector pins 40. And it is respectfully submitted that Rogers et al does not at all disclose or suggest the features of the present invention as recited in new independent claims 23, 24 and 26 whereby the circuit board is integrally formed by providing a metal foil on a resin plate having projected anchor pins, and punching a circuit pattern out of the metal foil, wherein the circuit pattern is fixed onto the resin plate by the anchor pins, reception terminals are inserted into terminal receiving holes formed in the resin plate, and tab portions which are provided on the reception terminals are fixed to the circuit pattern by welding.

In addition, it is respectfully pointed out that Nakayama has merely been cited for the disclosure of a plate comprising insulating synthetic resin. And it is respectfully submitted that Ishii, Ogawa et al and Rosli et al fail to disclose or suggest the above described features of the claimed present invention.

In view of the foregoing, it is respectfully submitted that the present invention as recited in new independent claims 23, 24 and 26, and claims 25 and 27-33 respectively depending from new independent claims 24 and 26, clearly patentably distinguishes over all of the cited references, taken singly or in any combination, under 35 USC 103.

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Entry of this Amendment, allowance of the claims and the passing of this application to issue are respectfully solicited.

If the Examiner has any comments, questions, objections or recommendations, the Examiner is invited to telephone the undersigned for prompt action.

Respectfully submitted,

/Douglas Holtz/

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